

**Amendment and Response Under 37 C.F.R. 1.116**

Applicant: Michael Bauer et al.

Serial No.: 10/789,033

Filed: February 27, 2004

Docket No.: I431.103.101/FIN423US

Title: ELECTRONIC COMPONENT AND SEMICONDUCTOR WAFER, AND METHOD FOR PRODUCING THE SAME

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**IN THE CLAIMS**

Please cancel claims 1-5 and 15-20.

Please amend claims 6-14 as follows:

1.-5. (Cancelled)

6. (Currently Amended) A semiconductor chip system, comprising: with  
a plurality of semiconductor chips, each having:  
a top side, a rear side opposite and parallel to the top side, and ~~with~~ edge sides, ~~the~~  
~~semiconductor chip comprising:~~  
an integrated circuit on the top side;  
at least one edge side having edge contacts wherein, the edge contacts extend from  
the top side in the direction of the rear side of the semiconductor chip; ~~and~~  
wherein the edge contacts are connected to electrodes of the integrated circuit via  
conductor tracks located on the top surface of the semiconductor chip; and  
a circuit substrate having a top side with external contacts, wherein ~~a plurality of~~  
~~additional~~ the semiconductor chips are ~~stacked one on the other and are~~ electrically connected  
via the edge contacts among one another and also with respect to the external contacts on ~~an~~  
~~insulated~~ a the circuit substrate such that the top and rear sides of the semiconductor ~~wafers~~ chips  
are oriented virtually perpendicular to the ~~a~~ top side of the circuit substrate.

7. (Currently amended) The semiconductor chip system of claim 6, wherein the edge sides  
have a perforation-like structure, semicylinder-like cutouts extending as edge contacts from the  
top side in the direction of the rear side, and have a metal layer.

8. (Currently amended) The semiconductor chip system of claim 7, wherein the edge sides  
also have an insulation layer.

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9. (Currently amended) The semiconductor chip system of claim 7, wherein the cutouts have a soldering material.

10. (Currently amended) The semiconductor chip system of claim 7, wherein the edge contacts are extended on the top side to form a contact area and merge with a conductor track on the top side.

11. (Currently amended) The semiconductor chip system of claim 7, wherein the semiconductor chips are arranged on the circuit substrate within an electronic component.

12. (Currently amended) The semiconductor chip system of claim 11, wherein the external contacts on the top side of the circuit substrate has is a conductor track structure having conductive lines running in parallel, the semiconductor chip being arranged with its rear side on the top side of the circuit substrate and the edge contacts being electrically connected to the conductor track structure via contact pads on the top side of the circuit substrate.

13. (Currently amended) The semiconductor chip system of claim 12, wherein an insulating plastics composition is arranged on the circuit substrate in a manner embedding the edge sides of the semiconductor chip and the contact pads.

14. (Currently amended) The semiconductor chip system of claim 12, wherein the semiconductor chip is arranged with an edge side on the circuit substrate, the top side of the semiconductor chip being arranged in angular fashion with respect to the top side of the circuit substrate and the edge contacts being electrically connected to the contact pads.

15-20. (Cancelled)